

## P-Channel 20-V (D-S) MOSFET

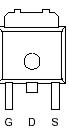
These miniature surface mount MOSFETs utilize High Cell Density process. Low  $r_{DS(on)}$  assures minimal power loss and conserves energy, making this device ideal for use in power management circuitry. Typical applications are PWMDC-DC converters, power management in portable and battery-powered products such as computers, printers, battery charger, telecommunication power system, and telephones power system.

- Low r<sub>DS(on)</sub> Provides Higher Efficiency and Extends Battery Life
- Miniature TO-252 Surface Mount Package Saves Board Space
- High power and current handling capability
- Extended VGS range (±25) for battery pack applications

PRODUCT SUMMARY			
V <sub>DS</sub> (V)	$r_{\mathrm{DS(on)}} m(\Omega)$	I <sub>D</sub> (A)	
-2.0	$59 @ V_{GS} = -4.5V$	24	
-20	$95 @ V_{GS} = -2.5V$	19	

TO-252





Top View

ABSOLUTE MAXIMUM RATINGS ( $T_A = 25$ °C UNLESS OTHERWISE NOTED)						
Parameter			Maximum	Units		
Drain-Source Voltage		$V_{DS}$	-20	V		
Gate-Source Voltage		V <sub>GS</sub>	±12	v		
Continuous Drain Current <sup>a</sup>	$T_A=25^{\circ}C$	I <sub>D</sub>	24	А		
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	±40	A		
Continuous Source Current (Diode Conduction) <sup>a</sup>			-30	А		
Power Dissipation <sup>a</sup>	T <sub>A</sub> =25°C	P <sub>D</sub>	50	W		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to 175	°C		

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Maximum	Units		
Maximum Junction-to-Ambient <sup>a</sup>	$R_{\theta JA}$	50	°C/W		
Maximum Junction-to-Case	$R_{\theta JC}$	3.0	°C/W		

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

b. Pulse width limited by maximum junction temperature

Parameter	Symbol	Test Conditions	Limits			TLA
	Symbol	Test Conditions	Min	Тур	Max	Unit
Static						
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = -250 \text{ uA}$	-0.7			
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 25 V$			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = -16 V, V_{GS} = 0 V$			-1	uA
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^{\circ}\text{C}$			-5	
On-State Drain Current <sup>A</sup>	I <sub>D(on)</sub>	$V_{DS} = -5 V, V_{GS} = -4.5 V$	-41			Α
Durin Course On Desisters A	r <sub>DS(on)</sub>	$V_{GS} = -4.5 \text{ V}, I_D = -24 \text{ A}$			59	mΩ
Drain-Source On-Resistance <sup>A</sup>		$V_{GS} = -2.5 \text{ V}, I_D = -19 \text{ A}$			95	
Forward Tranconductance <sup>A</sup>	g <sub>fs</sub>	$V_{DS} = -10 \text{ V}, I_D = -24 \text{ A}$		31		S
Diode Forward Voltage	V <sub>SD</sub>	$I_{S} = -41 \text{ A}, V_{GS} = 0 \text{ V}$		-0.7		V
Dynamic <sup>b</sup>						
Total Gate Charge	Qg	X = 10 X X = 45 X		16.7		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V},$ $I_{D} = -24 \text{ A}$		1.8		nC
Gate-Drain Charge	Q <sub>gd</sub>	$I_D = -24 A$		1.9		
Switching						
Turn-On Delay Time	t <sub>d(on)</sub>			15		
Rise Time	t <sub>r</sub>	$V_{DD}$ = -10 V, $R_L$ = 15 $\Omega$ , ID = -24		12		nS
Turn-Off Delay Time	t <sub>d(off)</sub>	A, $VGEN = -10 V$ , $RG = 6\Omega$		62		
Fall-Time	t <sub>f</sub>			46		1

Notes

- a. Pulse test:  $PW \le 300$ us duty cycle  $\le 2\%$ .
- b. Guaranteed by design, not subject to production testing.